



## Product / Process Change Notification (PCN)

- Major change  
 Minor change

**PCN #:** PCN\_WE-CBA\_20240105  
**Affected Series:** WE-CBA-Series; 782422xxx; 782423xxx  
**PCN Date:** July 05, 2023  
**Effective Date:** January 05, 2024

- Change Category:**
- Equipment / Location
  - General Data
  - Material
  - Process
  - Product Design
  - Shipping / Packaging
  - Supplier
  - Software

**Contact:** Product Management  
**Phone:** +49 (0) 7942 - 945 5001  
**Fax:** +49 (0) 7942 - 945 5179  
**E-Mail:** pcn.eisos@we-online.com

- Data Sheet Change:**
- Yes       No
- Attachment:**
- Yes       No

### Description and purpose of change:

To increase the production capability, Würth Elektronik will change the printing process. With this change and in order to improve product reliability, Würth Elektronik will adjust the internal design of the parts to meet the specified electrical characteristics.

There will be no change in form, fit or function of the product.

### Detail of Change:

PN starting with 782422xxx and 782423xxx will change the printing process. In order to maintain the same specifications as in the datasheet, adjustments will be made in the parts concerning number of turns, the material and the in-out trace. All these changes aim to improve the reliability and production capability of the product.



### **Reliability / Qualification Summary:**

Product approval is according to the specification criteria and is internally released by the Product Management Department.

### **The following items are part of the internal release process:**

- High Temperature Exposure / MIL-STD-202, Method 108
- Temperature Cycling / JESD22, Method JA-104
- Biased Humidity / MIL-STD-222, Method 103
- Operational Life / MIL-STD-202-108
- External Visual / MIL-STD-883 Method 2009
- Physical Dimension / JESD22 Method JB-100
- Resistance to Solvents / MIL-STD-202 Method 215
- Mechanical Shock / MIL-STD-202 Method 213
- Vibration / MIL-STD-202 Method 204
- Resistance to Soldering Heat / MIL-STD-202, Method 210
- ESD / AEC-Q200-002 or ISO/DIS10605
- Solderability /IPC-A-610
- Electrical Characterization / User Spec.
- Board Flex / AEC-Q200-005
- Terminal Strength (SMD) / AEC-Q200-006
- Low Temperature Storage Life / JESD22-A119